

Tuesday, November 12, 2024		
Time		
5:00 to 7:00 PM	EVENT RECEPTION (appetizers, wine and beer) and EXHIBIT TABLES in ROOM 220C	
Wednesday, November 13, 2024		
Time	Program	Lead/Speaker
7:00 to 8:30 AM	BUFFET BREAKFAST in ROOM 220C	
8:30 AM	Chair Welcome followed by IEEE President presentation	Michael Condry, IEEE Fellow Tom Coughlin, IEEE President
9:00 AM	AI Infrastructure: We CAN Close the AI Energy Gap	David Tennenhouse, Senior Advisor, National Science Foundation
9:30 AM	AI APPLICATIONS SESSION	Stoyan Nihtianov, IEEE, Chair
9:45 AM	Empowering Industrial Customers: Practical Applications of Generative AI	Jürgen Weichenberger, VP, Schneider Electric
10:15 AM	Transforming Chip to Data Center Design with Generative AI	Venkat Thanvantri, Corporate VP, Cadence
10:45 AM	COFFEE BREAK and EXHIBIT TABLES in ROOM 220C	
11:00 AM	The Evolution of Digital Twins: Applications and Opportunities for Semiconductor Manufacturing and Other Industries	Dan Isaacs, CTO, Digital Twin Consortium
11:30 AM	Applications of AI in Holistic Lithography	Yu Cao, SVP, Head of AI Program and Strategy, ASML
12:00 PM	The Future of AI Infrastructure in Medicine	Ronjon Nag, Founder, R42
12:30 PM	LUNCH and EXHIBIT TABLES in ROOM 220C	
1:30 PM	SILICON SESSION	Frank Schirrmester, Executive Director, Strategic Programs, System Solutions, Synopsys, Chair
1:45 PM	Reliability, Availability, and Serviceability in the Age of AI	Zane Ball, VP, Intel
2:15 PM	Semiconductor Technology Innovations to Fuel the Chip Engine for AI Infrastructure	Huiming Bu, VP, IBM
2:45 PM	COFFEE BREAK and EXHIBIT TABLES in ROOM 220C	
3:15 PM	Customization & Energy-efficiency Improvement with Advanced Packaging for AI Infrastructure	Woopoung (Vincent) Kim, Corporate EVP, Samsung Device Solutions Research America
3:45 PM	Next-generation Interconnect Technologies Driving the Evolution of AI Hypercomputing and TPUs	Sandeep Giri, SysInfra PMO, Google
4:15 PM	Redefining Limits in Semiconductor Engineering for AI with AI	Alex Starr, Corporate Fellow, AMD
4:45 PM	Navigating Power, Security and Thermal Considerations for the Future AI Infrastructure Semiconductor Landscape	Vojin Zivojnovic, AGGIOS
5:15 PM	Session Ends	
Thursday, November 14, 2024		
Time	Program	Lead/Speaker
7:00 to 8:30 AM	BUFFET BREAKFAST in ROOM 220C	
8:30 AM	SYSTEMS SESSION INTRODUCTION	Steve Jordan, President, Jordan Consulting Group, Chair
8:45 AM	The Utility Challenges to Deliver Power to Large Data Centers	Jessica Bian, VP Grid Services, Grid-X Partners
9:15 AM	Energy Independence and the BYOP Strategy	Peter Panfil, Vice President of Global Power, Vertiv
9:45 AM	Reducing the Barriers to Training AI Foundation Models	Paolo Faraboschi, VP and Fellow, HP Enterprise
10:15 AM	COFFEE BREAK and EXHIBIT TABLES in ROOM 220C	
10:30 AM	How Generative AI and Accelerated Compute Are Creating the Next Generation of Liquid Cooled Data Centers	Ali Heydari, Distinguished Engineer, NVIDIA
11:00 AM	Gas Turbine Prime Power Solutions for Large Datacenters: Low Carbon, Dispatchable Power, with Examples from Other Industries	Matt Davidsaver, Product Manager, GE Vernova
11:30 AM	Moderated Discussion	
11:45 AM	LUNCH and EXHIBIT TABLES in ROOM 220C	
1:00 PM	SECURITY AND STANDARDS SESSION	David Snyder, President, 42TEK LLC, Chair
1:30 PM	Cybersecurity for Agentic AI	Omar Santos, Distinguished Engineer, Cisco
2:00 PM	Our Secure Quantum Future	Jaya Baloo, CSO, Rapid7
2:30 PM	Secure Sharing of GenAI/LLMs With Post Quantum Encryption	Wally Rhines, CEO, Cornami
3:00 PM	COFFEE BREAK and EXHIBIT TABLES in ROOM 220C	
3:30 PM	Developing and Deploying Industry Standards for Artificial Intelligence: Challenges, Strategies, and Future Directions	Richard Tong, Chair, IEEE Artificial Intelligence Standards Committee
4:00 PM	AI and Intellectual Property	David Sanker, Patent Attorney, SankerIP
4:30 PM	The Laws, Policies & Regulations Shaping the Future of AI	Brandie Nonnecke, Founding Director, CITRIS Policy Lab
5:00 PM	Moderated discussion	
5:45 PM	Closing remarks	
		Chairs